Product End-of-Life Disassembly Instructions

Product Category: Chromebox
Marketing Name / Model [List multiple models if applicable.]
HP Chromebox G4 ENERGY STAR
HP Chromebox Enterprise G4 ENERGY STAR
TPN-Q290

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	☒ Main board (MB) PCB ☒ Solid state drive (SSD) PCB ☒ Wireless WAN module (WWAN) PCB ☐ Touch module PCB ☐ Power supply PCB ☐ External Keyboard (KB) ☐ External Mouse ☐ Others: _Power board, RAM_____________	5
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	☒ RTC/CMOS battery ☐ Others: ______________	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: ☐ screws ☐ snaps ☐ adhesive ☐ other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	☐ Panel LCD	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	☐ Power Supply capacitor(s) or condenser(s)	0
External electrical cables and cords	☒ AC power cord ☐ Audio, video or data cables ☐ Other: __________	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	Philip #0
Screwdriver	Philip #1

3.0 Product Disassembly Process

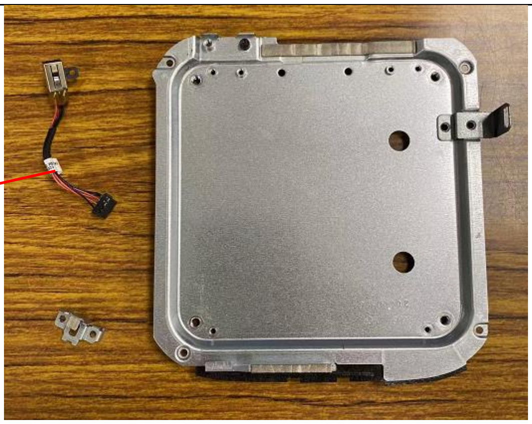
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

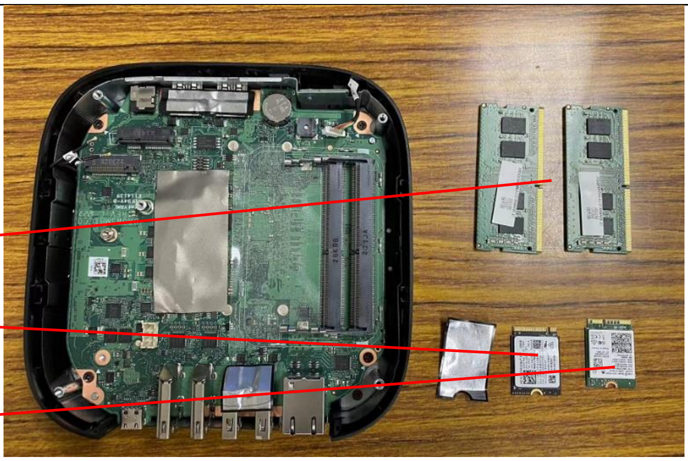
1. Remove the Bottom Cover Rubber feet.
2. Dis-fasten Bottom Cover Screw*4
3. Remove the Bottom Cover
4. Dis-fasten IO Frame Screw*2
5. Remove the IO Frame
6. Dis-fasten Bottom Shielding Screw*4
7. Remove the Bottom Shielding
8. Dis-fasten DC Bracket Screw*2
9. Remove the DC Bracket & DC Cable
10. Remove Antenna Mylar & Antenna terminal & Power Cable
11. Dis-fasten WLAN Card Screw & SSD Screw & Shielding can
12. Remove WLAN Card & SSD Mylar & SSD & RAM
13. Dis-fasten MB Screw*4
14. Remove Main Board
15. Dis-fasten FAN Screw*3
16. Dis-fasten FAN Screw*4 & Remove FAN
17. Remove Thermal module
18. Dis-fasten Top Shielding Screw*4
19. Remove Top Shielding
20. Dis-fasten Power Board Screw*2
21. Remove Power Board & Power Cable
22. Remove Antenna & Mylar

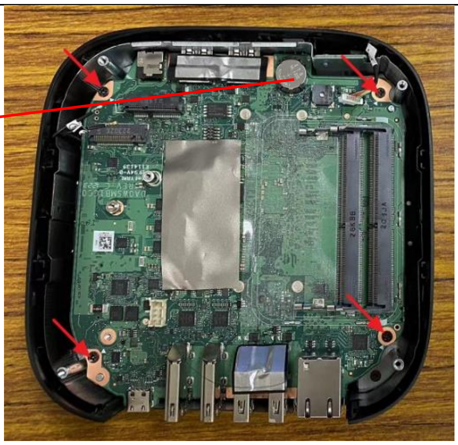
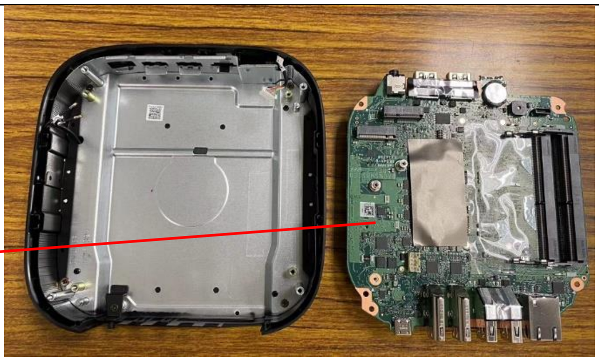
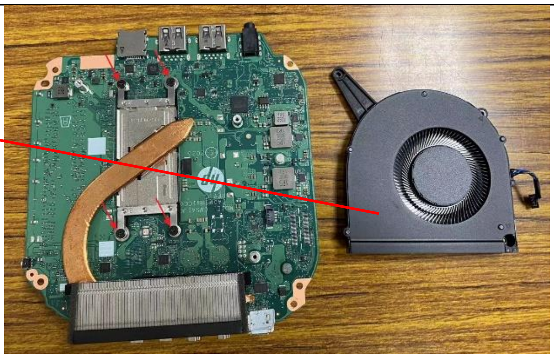
3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: End-of-Life Product Disassembly Instructions (hp.com)

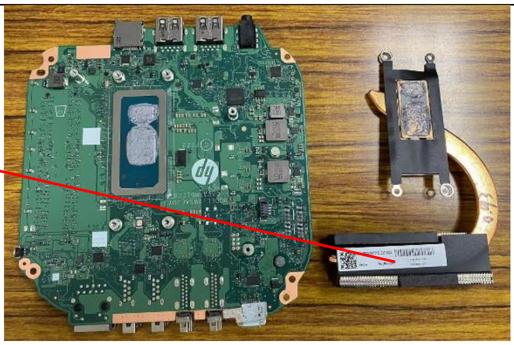
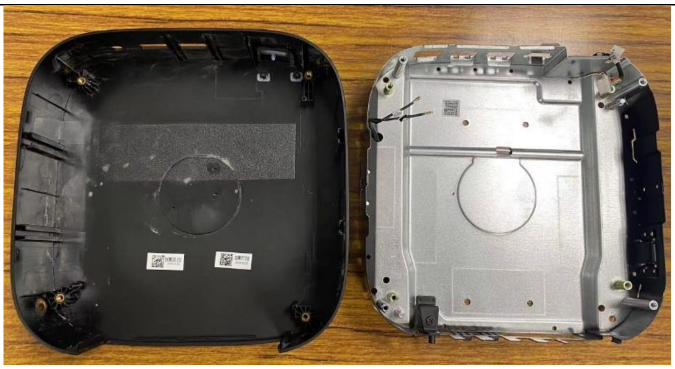
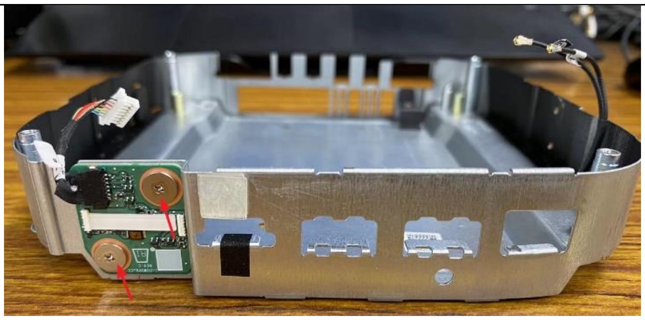
1. Remove the Bottom Cover Rubber feet.	

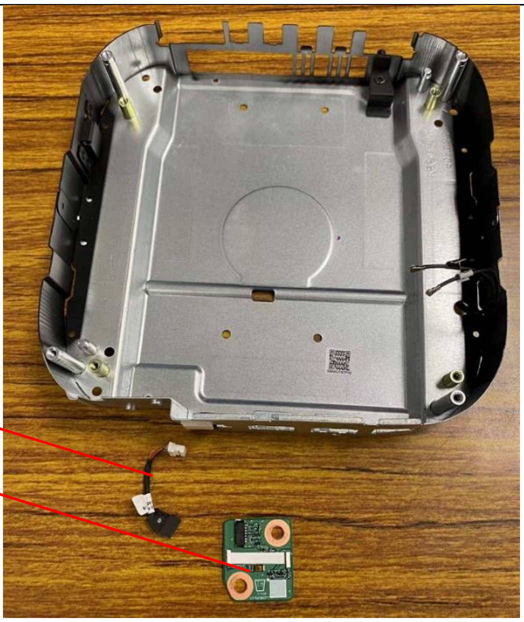
2. Dis-fasten Bottom Cover Screw*4	
3. Remove the Bottom Cover	
4. Dis-fasten IO Frame Screw*2	
5. Remove the IO Frame	

6. Dis-fasten Bottom Shielding Screw*4	
7. Remove the Bottom Shielding	
8. Dis-fasten DC Bracket Screw*2	
9. Remove the DC Bracket & DC Cable	

10. Remove Antenna Mylar & Antenna terminal & Power Cable	
11. Dis-fasten WLAN Card Screw & SSD Screw & Shielding can	
12. Remove WLAN Card & SSD Mylar & SSD & RAM RAM SSD WLAN Card	

13. Dis-fasten MB Screw*4 Coin battery	
14. Remove Main Board Main Board	
15. Dis-fasten FAN Screw*3	
16. Dis-fasten FAN Screw*4 & Remove FAN Fan	

17. Remove Thermal module	
18. Dis-fasten Top Shielding Screw*4	
19. Remove Top Shielding	
20. Dis-fasten Power Board Screw*2	

21. Remove Power Board & Power Cable Power Cable Power Board	
22. Remove Antenna & Mylar Antenna